Device Material Content

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Package: 100 TQFP (1.4mm)
Total Device Weight 0.650 Grams

Package Code: TN100
Products: LAMXO

Assembly: ASEM
Size (mm): 14 x 14 x 1.4
Lead pitch (mm): 0.5
MSL: 3
Reflow max (°C): 260

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.45%	0.0094			Silicon chip	7440-21-3	100.00%	Die size: 3.35 x 3.35 mm
Mold Compound	77.02%	0.5006	4.62%	0.0300	Epoxy Resins	-	6.00%	Mold Compound: Hitachi CEL9220HF
			3.85%	0.0250	Phenol Resin	-	5.00%	
			0.15%	0.0010	Carbon Black	1333-86-4	0.20%	
			65.62%	0.4265	Silica	60676-86-0	85.20%	
			2.77%	0.0180	Other (trade secret)	-	3.60%	
D/A Epoxy	0.18%	0.0011	0.14%	0.0009	Silver (Ag)	7440-22-4	80.00%	Die attach: Ablebond 3230
			0.04%	0.0002	other	-	20.00%	
Wire	0.29%	0.0019	0.29%	0.0019	Gold (Au)	7440-57-5	100.00%	0.8 mil wire diameter; 1 wire for each package lead
Plating	1.83%	0.0119	1.83%	0.0119	Tin (Sn)	7440-31-5	100.00%	Plating is 100% Matte Sn; thickness is >10.2µm
Leadframe	19.23%	0.1250	18.60%	0.1209	Copper (Cu)	7440-50-8	96.70%	C7025
			0.58%	0.0038	Nickel (Ni)	7440-02-0	3.01%	
			0.03%	0.0002	Silicon (Si)	7440-21-3	0.17%	
			0.01%	0.0000	Magnesium (Mg)	7439-95-4	0.03%	
			0.02%	0.0001	Silver (Ag)	7440-22-4	0.09%	

Notes:
The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.
Constituent substances and proportions in epoxy materials are before curing.
The information provided above is representative of the package as of the date listed, and is subject to change at any time.
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Br/Cl/Sb
Pb lead-free
RoHS

Rev. B